# **GP2W0004YP**

#### Features

- 1. Compliant with IrDA1.0
- Integrated package of transmitter/receiver.
  (9.21×3.76×height 2.71mm)
- 3. General purpose
- 4. Low dissipation current due to shut-down function (Dissipation current at shut-down mode:Max. 1.0μA)
- 5. Soldering reflow type
- 6. Shield type

#### ■ Applications

- 1. Cellular phones, PHS
- 2. Personal information tools

Parameter	Symbol	Rating	Unit	
Supply voltage	V <sub>CC</sub>	0 to 6.0	V	
LED Supply voltage	V <sub>LEDA</sub>	0 to 7.0	V	
Forward current	I <sub>F</sub>	50	mA	
*1 Peak forward current	I <sub>FM</sub>	600	mA	
Operating temperature	Topr	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-25 to +85	°C	
*2 Soldering temperature	T <sub>sol</sub>	240	°C	

### ■ Absolute Maximum Ratings (T<sub>a</sub>=25°C)

#### \*1 Pulse width 115.2kb/s, Duty ratio :3/16

\*2 For MAX. 10s

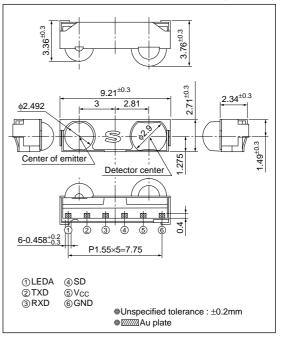
#### Recommended Operating Conditions

Parameter	Symbol	Rating	Unit	
Supply voltage	V <sub>CC</sub>	2.4 to 5.5	V	
Transmission rate	BR	2.4 to 115.2	kb/s	
LED Supply Voltage	V <sub>LEDA</sub>	2.4 to 7.0	V	
Operating temperature	T <sub>opr</sub>	-25 to +85	°C	

## IrDA Transceiver Module Compliant with IrDA1.0

#### Outline Dimensions

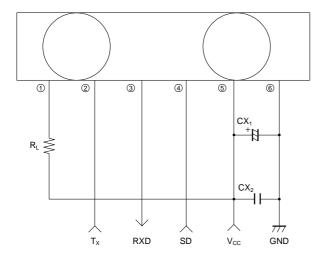
(Unit : mm)



E E	Electrical Characteris	tics				(T <sub>a</sub> =25°C,	V <sub>CC</sub> =3.3V)
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Dissipation current at no input signal	I <sub>CC</sub>	No input light, output terminal open, V <sub>ILSD</sub> =0V	-	110	130	μΑ
	S/D dissipation current	I <sub>CC-S</sub>	No input light, output terminal open, $V_{IHSD}$ =V <sub>CC</sub>	_	0.01	1.0	μΑ
Receiver side	High level output voltage	V <sub>OH1</sub>	V <sub>CC</sub> =5V, I <sub>OH</sub> =500µA	4.3	4.6	-	V
		V <sub>OH2</sub>	V <sub>CC</sub> =2.4V, I <sub>OH</sub> =500µA	1.5	1.7	-	V
	Low level output voltage	V <sub>OL1</sub>	$V_{CC}=5V, I_{OL}=500\mu A^{*3}$	-	0.22	0.4	V
		V <sub>OL2</sub>	V <sub>CC</sub> =2.4V, I <sub>OL</sub> =300µA <sup>*3</sup>	_	0.17	0.3	V
ece	Pules width	t <sub>w</sub>	BR=9.6kb/s, 115.2kb/s*3	1.0	2.4	3.6	μs
В	Rise time	t <sub>r</sub>	V <sub>CC</sub> =5.0V, C <sub>L</sub> =15pF	-	18	27	ns
	Fall time	t <sub>f</sub>	V <sub>CC</sub> =5.0V, C <sub>L</sub> =15pF	_	18	27	ns
	Maximum communication distance	L	Voh, Vol, tw, tr, tf $^{*3}$ shall be satisfied at $\phi \leq 15^{\circ}$	1	-	-	m
mitter Je	Radiant intensity	$I_E$	DD 115 011/2 $+ < 15^{\circ}$ V 2 2V *4	40	-	-	mW/sr
Transmitter	Peak emission wavelength	$\lambda_p$	BR=115.2kb/s, φ≤15°, Vleda=3.3V *4	850	870	900	nm

\*3 Refer to Fig.3, 4, 5 \*4 Refer to Fig.6, 7, 8

#### Fig.1 Recommended External Circuit



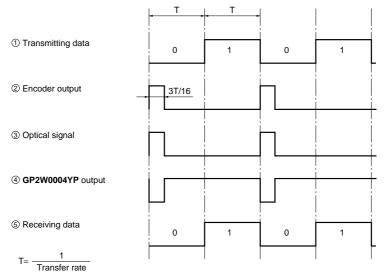
Components circuit	Recommend values		
CX1	*22µF		
CX <sub>2</sub>	*0.1µF		
R∟	(Table1)		

 $^{\ast}$  Please choose the most suitable CX1 and CX2 according to the noise level and noise frequency of power supply.

Table1	
VLED	R∟
2.4≤Vled≤3.6V	0Ω±5%, 0.5W
3.5≤Vled≤4.8V	1.3Ω±5%, 0.5W
4.5≤Vled≤5.5V	2.7Ω±5%, 0.5W

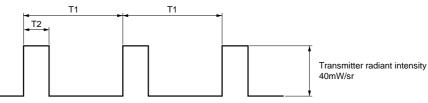
LEDA
 TXD
 RXD
 SD
 V<sub>CC</sub>
 GND

### Fig.2 Example of Signal Waveform



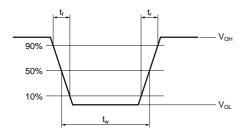
Transfer rate ; 2.4kb/s,9.6kb/s,19.2kb/s,38.4kb/s,57.6kb/s,115.2kb/s

#### Fig.3 Input Signal Waveforrm(Receiver side)

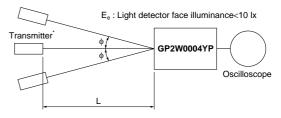


At BR=9.6kb/s:T1=104.2µs, T2=19.5µs At BR=115.2kb/s:T1=8.68µs, T2=1.63µs

## Fig.4 Output Waveform Specification (Receiver side)



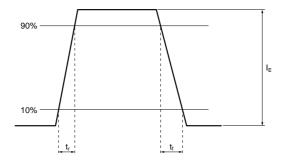
## Fig.5 Standard Optical System (Receiver side)



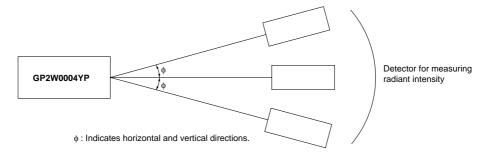
 $\boldsymbol{\phi}$  : Indicates horizontal and vertical directions.

\* Transmitter shall use GP2W0004YP ( $\lambda p{=}870nm$  TYP.) which is adjusted the radiation intensity at 40mW/sr

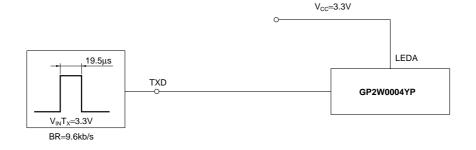
#### Fig.6 Output Waveform Specification(Transmitter side)



#### Fig.7 Standard Optical System(Transmitter side)

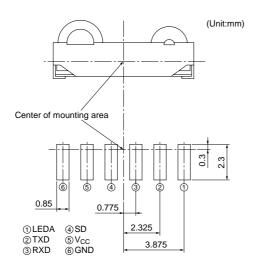


#### Fig.8 Recommended Circuit of Transmitter side



#### Fig.9 Recommended PCB Foot Pattern

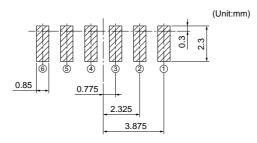
Dimensions are shown for reference



	Terminal	Symbol
1	LED anode	LEDA
2	Transmitter data input	TXD
3	Receiver data output	RXD
4	Shutdown	SD
5	Supply voltage	V <sub>cc</sub>
6	Ground	GND

#### Fig.10 Recommended Size of Solder Creamed Paste (Reference)

Please open the solder mask as below so that the size of solder creamed paste for this device before reflow soldering must be as large as one of the foot pattern land indicated Fig.9



Solder paste area

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